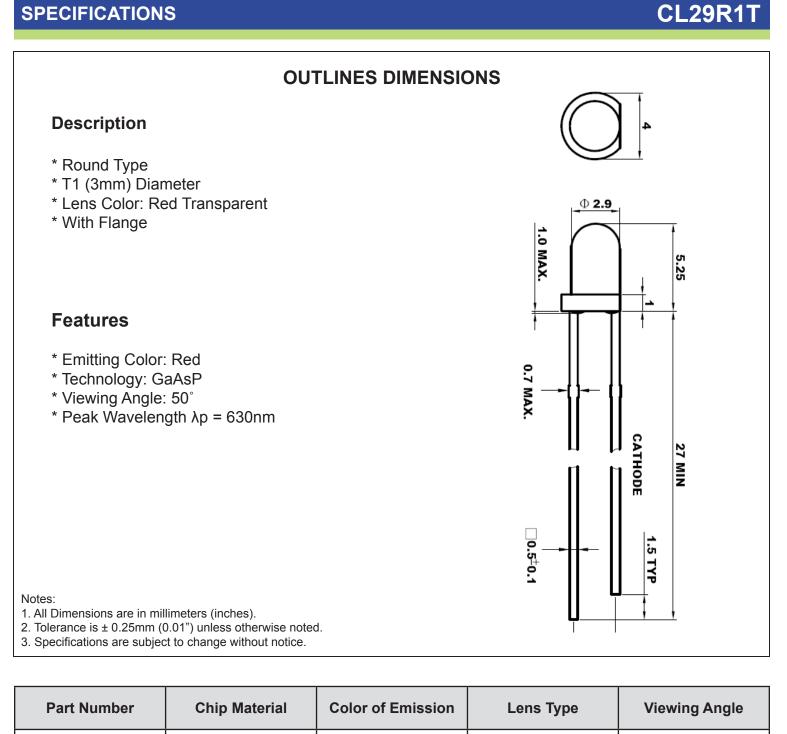


SPECIFICATIONS

CL29R1T

GaAsP





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50°

Red Transparent

Red



ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	Po	75	mW
Pulse Current Forward Current	IFP	100	mA
Continuous Forward Current	lF	30	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr	-40~+85	°C
Storage Temperature Range	Тѕтс	-40~+85	°C
IFP = Pulse Width \leq 10 ms, Duty Ratio \leq 1/10. Soldering Condition: 260 °C/ 5sec			

OPTICAL-ELECTRICAL CHARACTERISTICS

Value **Test Condition** Parameter Symbol Unit Min Тур Max 13 30 Luminous Intensity I_F = 10mA Iv _ mcd Forward Voltage I⊧ = 10mA 1.85 2.5 V VF _ **Reverse Leakage Current** $V_R = 5V$ IR 10 μA -_ **Viewing Angle** $2\theta 1/2$ I_F = 10mA 50 deg _ _ 630 Peak Wavelength I_F = 10mA λP _ nm _ Dominant Wavelength 620 λD I_F = 10mA nm _ _ 45 Spectral Line half-width I_F = 10mA Δλ _ nm _

*Tolerance of viewing angle: -10 / +5 deg.

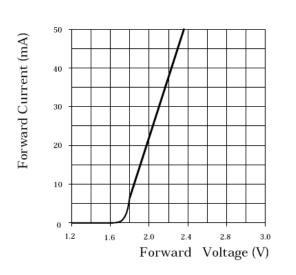


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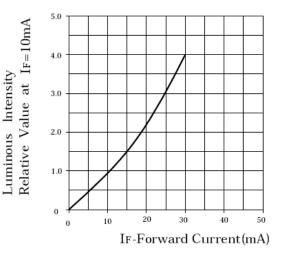
(TA=25°C)



OPTICAL CHARACTERISTIC CURVES

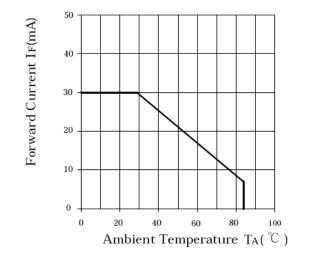


Forward Current vs. Forward Voltage



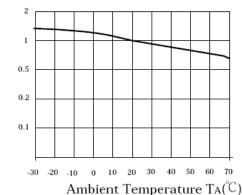
Relative Intensity vs. Forward Current

Luminous Intensity vs. Ambient Temperature



Forward Current vs. Ambient Temperature

Relative Luminous Intensity





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SOLDERING CONDITIONS – LAMP TYPE LED

- * Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.
- * Recommended soldering conditions

Dip Soldering		
Pre-Heat	100 °C Max	
Pre-Heat Time	60 Second Max	
Solder Bath Temperature	260 °C Max	
Dippng Time	5 Second Max	
Dipping Position	No lower than 3mm from the base of the epoxy	

Hand Soldering			
Temperature Soldering Time Position	3mm Series	Others	
	300 °C Max	350 °C Max	
	3 Second Max	3 Second Max	
	No closer than 3mm from the	No closer than 3mm from the	
	base of the epoxy	base of the epoxy	

- * Do not apply any stress to the lead. Particularly when heated.
- * The LED must not be repositioned after soldering.
- * After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- * Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- * When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- * Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.



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